

Driving decarbonization and digitalization. Together.



Senior Staff Engineer Package Development

Job description

In your new role you will:

- To provide technical support for new product introduction at subcons. Ensures that technical, quality, schedule and cost requirements are achieved.
- Responsible for technical support of new product/package/new process development.
- Ensure that the project meets customer requirements in terms of timeline, cost and quality
- Assess and mitigate technical risks.
- Provide design proposal for package, lead frame, substrate and Cu-clip of new products
- Close interaction with the project manager, subcon interface, chip designer, application team, marketing and business units for new product design and project roadmaps
- Provide technical direction related to problem solving of process and reliability issues.
- Closure of Package Development related deliverables and documents
- Technical Documentation thru Delta analysis DFMEA, PFMEA, Process Flow & Control plan.

Profile

You are best equipped for this task if you have:

- Master / Bachelor Degree in Engineering and Physical Science
- Minimum requirement 5 Years of Package/Process development in Semiconductor packaging
- Experience in semiconductor package development
- Analytical and self-driven
- Experience in analytical tools: Delta Analysis, DFMEA, DoE, 8D and simulation.
- Proficient in AutoCAD for 2D drawing. Knowledge using 3D software (e.g. AutoCAD 3D, Inventor, and SolidWorks) is an advantage
- Exposure to the development of a wide variety of packages: TO, QFN, Cu Clip, Flip Chip, SOIC, QFP
- Knowledge in package design rules
- Proficient in industry standards for package reliability test and qualifications
- Knowledge of FA techniques

At a glance

Location:

Job ID: **HRC0929762**

Start date: **as soon as possible**

Entry level: **5+ years**

Type: **Full time**

Contract: **Permanent**

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Job ID: **HRC0929762**
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Contact

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- Knowledgeable on assembly processes.
- Can interpret package simulation results. Knowledge in package simulation software (e.g. ANSYS, SolidWorks) for FEA & thermal analysis is an advantage
- Excellent in statistical analysis that can provide a clear direction based on package/process DOE
- Working knowledge of DFMEA during design phase and ability to create strategy to mitigate risk
- Knowledge in IP management and patent filing.

Benefits

- **Chengdu, :** Coaching, mentoring networking possibilities; Wide range of training offers & planning of career development; International assignments; Different career paths: Project Management, Technical Ladder, Management & Individual Contributor; Flexible working conditions; Medical coverage; On-site social counselling and works doctor, in Wuxi only.; Provision of health tips, health knowledge sharing, annual medical check; Employees in Shanghai are entitled to use a gym located close to the office for free; On-site canteen, in Wuxi only.; Private insurance offers in some sites.; Wage payment in case of sick leave; Corporate pension benefits in some sites.

Why Us

#WeAreIn for driving decarbonization and digitalization.

As a global leader in semiconductor solutions in power systems and IoT, Infineon enables game-changing solutions for green and efficient energy, clean and safe mobility, as well as smart and secure IoT. Together, we drive innovation and customer success, while caring for our people and empowering them to reach ambitious goals. Be a part of making life easier, safer and greener.

Are you in?

We are on a journey to create the best Infineon for everyone.

This means we embrace diversity and inclusion and welcome everyone for who they are. At Infineon, we offer a working environment characterized by trust, openness, respect and tolerance and are committed to give all applicants and employees equal opportunities. We base our recruiting decisions on the applicant´s experience and skills.

We look forward to receiving your resume, even if you do not entirely meet all the requirements of the job posting.

Please let your recruiter know if they need to pay special attention to something in order to enable your participation in the interview process.

[Click here](#) for more information about Diversity & Inclusion at Infineon.

